

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.43676	100.0	6.3
			Subtotal	0.43676	100	6.3
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01769	100.0	0.25513
	Pure metal	Aluminium (Al)	7429-90-5	0.32029	100.0	4.62
			Subtotal	0.33798	200	4.87513
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.73319	100.0	25
			Subtotal	1.73319	100	25
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02329	0.04	0.336
	Copper alloy	Iron (Fe)	7439-89-6	0.05824	0.1	0.84
	Copper alloy	Copper (Cu)	7440-50-8	58.15373	99.86	838.824
			Subtotal	58.23526	100	840
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.39272	8.7	48.9375
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.23949	16.0	90
	Filler	Silica fused	60676-86-0	29.24762	75.0	421.875
	Carbon Black	Carbon black	1333-86-4	0.11699	0.3	1.6875
			Subtotal	38.99682	100	562.5
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.013	5.0	0.1875
	Lead alloy	Silver (Ag)	7440-22-4	0.0065	2.5	0.09375
	Lead alloy	Lead (Pb)	7439-92-1	0.24048	92.5	3.46875
			Subtotal	0.25998	100	3.75
			Total	99.99999	100	1442.42513

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